



SOT1894-1

plastic small outline package; 14 leads; 9.9 mm x 3.9 mm x 1.35 mm body

26 May 2017

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SO14
Package type industry code	SO14
Package style descriptive code	SO (small outline)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	17-8-2016
Manufacturer package code	SOT1894

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		9.8	-	9.9	10	mm
E	package width		3.8	-	3.9	4	mm
A	seated height		-	-	-	1.75	mm
A ₂	package height		1.25	-	1.35	1.45	mm
e	nominal pitch		-	-	1.27	-	mm
n ₂	actual quantity of termination		-	-	14	-	



2. Package outline

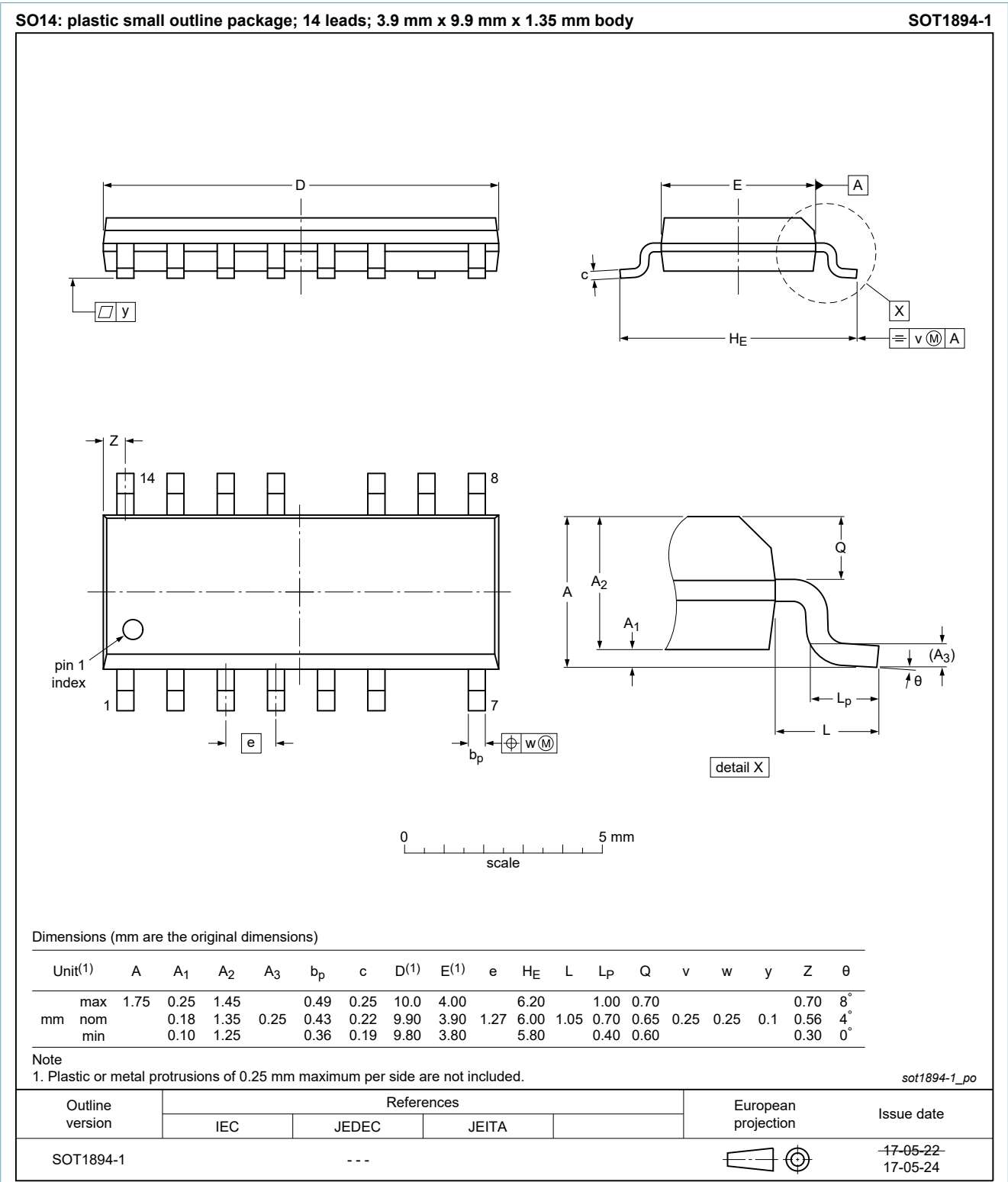


Fig. 1. Package outline SO14 (SOT1894-1)

3. Soldering

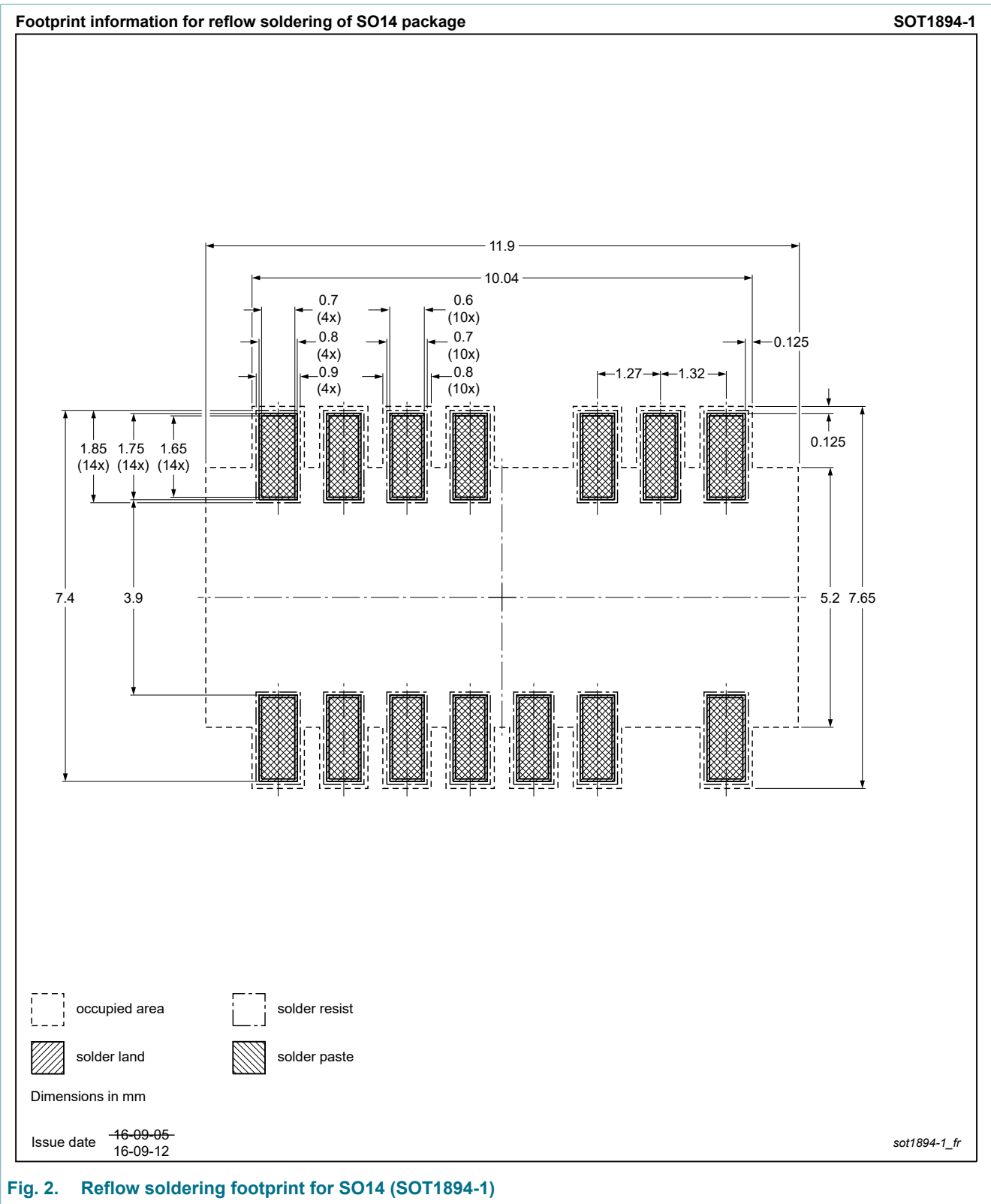


Fig. 2. Reflow soldering footprint for SO14 (SOT1894-1)

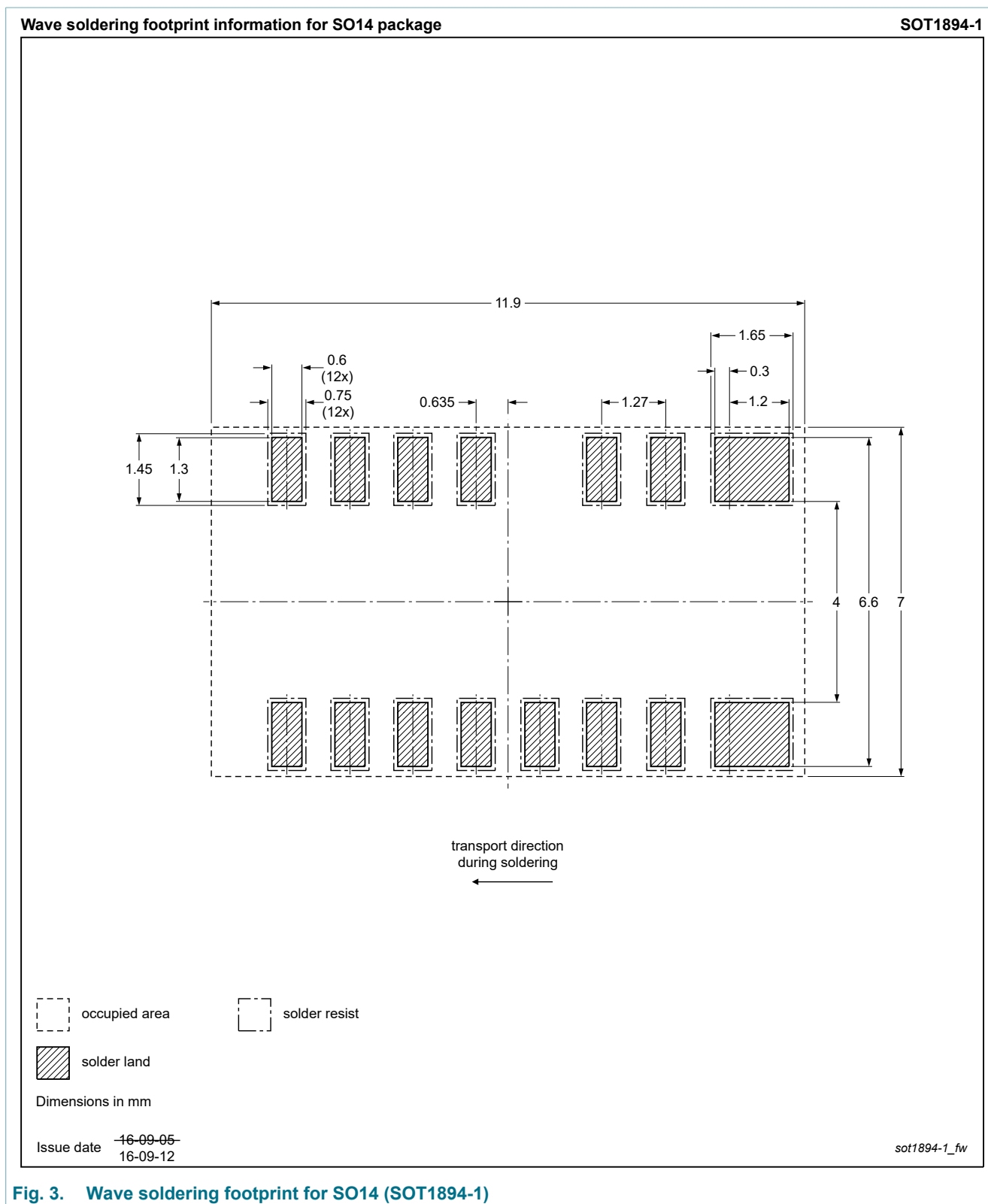


Fig. 3. Wave soldering footprint for SO14 (SOT1894-1)

4. Legal information

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